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RECC



102968463

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Ho-Yin YIU (01/24/2005), Fu-Jier FAN (01/24/2005), Yu-Jui WU (01/31/2005), Aaron WANG (01/24/2005),

Execution Date(s): in parentheses after inventor name

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

TAIWAN SEMICONDUCTOR
MANUFACTURING CO., LTD.

Name: _____

Internal Address: _____

Street Address: _____

No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park

City: Hsin-Chu

State: _____

Country: Taiwan ROC Zip: 300-77

Additional name(s) & address(es) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

4. Application or patent number(s):

A. Patent Application No.(s)
NEW

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Joe McKinney Muncy
BIRCH, STEWART, KOLASCH & BIRCH,
LLP

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Fax Number: (703) 205-8050

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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
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9. Signature:

Signature

March 17, 2005

Date

Joe McKinney Muncy - 32,334

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

KM/clb

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Additional Conveying Party(ies)/Execution Date(s) (1. Continued):

Hsiang-Wei WANG (01/24/2005), Huang-Sheng LIN (01/24/2005), Ming-Hsien CHEN (01/31/2005), and Ruey-Yun SHIUE (01/25/2005)

Additional Assignees (2. Continued):

Assignee Name: _____

Internal Address:

Street Address:

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address:

Street Address:

City: _____ State: _____ Country: _____ Zip: _____

Assignee Name: _____

Internal Address:

Street Address:

City: _____ State: _____ Country: _____ Zip: _____

Additional Applications and/or Patents (4. Continued):

Additional Patent Application Numbers
4A. Continued:

Additional Patent Numbers
4B. Continued:

Additional numbers attached?

Yes

No

ASSIGNMENT

WHEREAS, Ho-Yin YIU, Fu-Jier FAN, Yu-Jui WU, Aaron WANG Hsiang-Wei WANG, Huang-Sheng LIN, Ming-Hsien CHEN and Ruey-Yun SHIUE hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

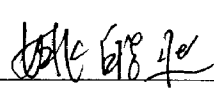
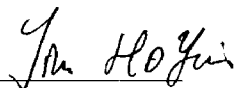
Title: TOP VIA PATTERN FOR BOND PAD STRUCTURE
Filed: 3/17/05 Serial No. NEW
Executed on: January 24, 2005, January 25, 2005, January 31, 2005

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Ho-Yin YIU

24-Jan-2005

Date:



Fu-Jier FAN

24-Jan-2005

Date:

Yu-Jui Wu

Yu-Jui WU

Jan 31 '05

Date:

Aaron Wang

Aaron WANG

Jan 24 '05

Date:

WANG HSIANG WEI

Hsiang-Wei WANG

Jan 24 '05

Date:

Huang Sheng Lin

Huang-Sheng LIN

Jan 24 '05

Date:

Ming-Hsien Chen

Ming-Hsien CHEN

Jan 31 '05

Date:

Ruey Yun Shiue

Ruey-Yun SHIUE

Jan 25 '05

Date: